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**Understanding Embedded - CPLDs (Complex Programmable Logic Devices)** 

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

#### **Applications of Embedded - CPLDs**

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	16
Number of Macrocells	64
Number of Gates	2000
Number of I/O	64
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/isplsi-2064a-80ltn100

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# ispLSI® 2064/A

In-System Programmable High Density PLD

#### **Features**

#### • ENHANCEMENTS

- ispLSI 2064A is Fully Form and Function Compatible to the ispLSI 2064, with Identical Timing Specifications and Packaging
- ispLSI 2064A is Built on an Advanced 0.35 Micron E<sup>2</sup>CMOS<sup>®</sup> Technology

#### • HIGH DENSITY PROGRAMMABLE LOGIC

- 2000 PLD Gates
- 64 I/O Pins, Four Dedicated Inputs
- 64 Registers
- High Speed Global Interconnect
- Wide Input Gating for Fast Counters, State Machines, Address Decoders, etc.
- Small Logic Block Size for Random Logic

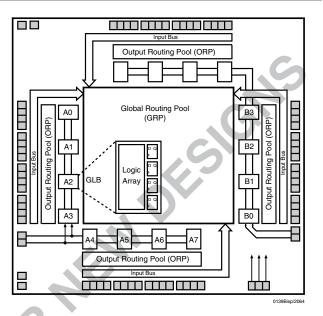
#### HIGH PERFORMANCE E<sup>2</sup>CMOS<sup>®</sup> TECHNOLOGY

- fmax = 125 MHz Maximum Operating Frequency
- tpd = 7.5 ns Propagation Delay
- TTL Compatible Inputs and Outputs
- Electrically Erasable and Reprogrammable
- Non-Volatile
- 100% Tested at Time of Manufacture
- Unused Product Term Shutdown Saves Power

#### • IN-SYSTEM PROGRAMMABLE

- In-System Programmable (ISP™) 5V Only
- Increased Manufacturing Yields, Reduced Time-to-Market and Improved Product Quality
- Reprogram Soldered Devices for Faster Prototyping
- OFFERS THE EASE OF USE AND FAST SYSTEM SPEED OF PLDs WITH THE DENSITY AND FLEXIBILITY OF FIELD PROGRAMMABLE GATE ARRAYS
- Complete Programmable Device Can Combine Glue Logic and Structured Designs
- Enhanced Pin Locking Capability
- Three Dedicated Clock Input Pins
- Synchronous and Asynchronous Clocks
- Programmable Output Slew Rate Control to Minimize Switching Noise
- Flexible Pin Placement
- Optimized Global Routing Pool Provides Global Interconnectivity
- Lead-Free Package Options

## **Functional Block Diagram**



## **Description**

The ispLSI 2064 and 2064A are High Density Programmable Logic Devices. The devices contain 64 Registers, 64 Universal I/O pins, four Dedicated Input pins, three Dedicated Clock Input pins, two dedicated Global OE input pins and a Global Routing Pool (GRP). The GRP provides complete interconnectivity between all of these elements. The 2064 and 2064A feature 5V in-system programmability and in-system diagnostic capabilities. The ispLSI 2064 and 2064A offer non-volatile reprogrammability of the logic, as well as the interconnect, to provide truly reconfigurable systems.

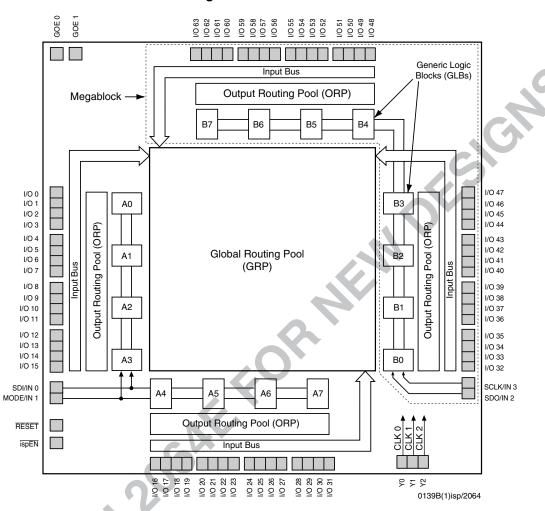
The basic unit of logic on these devices is the Generic Logic Block (GLB). The GLBs are labeled A0, A1...B7 (Figure 1). There are a total of 16 GLBs in the ispLSI 2064 and 2064A devices. Each GLB is made up of four macrocells. Each GLB has 18 inputs, a programmable AND/OR/Exclusive OR array, and four outputs which can be configured to be either combinatorial or registered. Inputs to the GLB come from the GRP and dedicated inputs. All of the GLB outputs are brought back into the GRP so that they can be connected to the inputs of any GLB on the device.

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## **Functional Block Diagram**

Figure 1. ispLSI 2064/A Functional Block Diagram



The devices also have 64 I/O cells, each of which is directly connected to an I/O pin. Each I/O cell can be individually programmed to be a combinatorial input, output or bi-directional I/O pin with 3-state control. The signal levels are TTL compatible voltages and the output drivers can source 4 mA or sink 8 mA. Each output can be programmed independently for fast or slow output slew rate to minimize overall output switching noise.

Eight GLBs, 32 I/O cells, two dedicated inputs and two ORPs are connected together to make a Megablock (Figure 1). The outputs of the eight GLBs are connected to a set of 32 universal I/O cells by two ORPs. Each ispLSI 2064 and 2064A device contains two Megablocks.

The GRP has as its inputs, the outputs from all of the GLBs and all of the inputs from the bi-directional I/O cells. All of these signals are made available to the inputs of the GLBs. Delays through the GRP have been equalized to minimize timing skew.

Clocks in the ispLSI 2064 and 2064A devices are selected using the dedicated clock pins. Three dedicated clock pins (Y0, Y1, Y2) or an asynchronous clock can be selected on a GLB basis. The asynchronous or Product Term clock can be generated in any GLB for its own clock.



## Absolute Maximum Ratings <sup>1</sup>

Supply Voltage V <sub>cc</sub> 0.5 to +7.0V
Input Voltage Applied2.5 to V <sub>CC</sub> +1.0V
Off-State Output Voltage Applied2.5 to $V_{CC}$ +1.0V
Storage Temperature65 to 150°C
Case Temp. with Power Applied55 to 125°C
Max. Junction Temp. (T <sub>J</sub> ) with Power Applied 150°C

<sup>1.</sup> Stresses above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied (while programming, follow the programming specifications).

# **DC Recommended Operating Condition**

SYMBOL	PA	MIN.	MAX.	UNITS	
<b>V</b> CC	Cumply Voltage	Commercial $T_A = 0^{\circ}C$ to + $70^{\circ}C$	4.75	5.25	٧
VCC	Supply Voltage	Industrial $T_A = -40^{\circ}\text{C to} + 85^{\circ}\text{C}$	4.5	5.5	V
<b>V</b> IL	Input Low Voltage		0	0.8	V
<b>V</b> IH	Input High Voltage	,()	2.0	V <sub>cc</sub> +1	V

Table 2 - 0005/2064

## Capacitance (TA=25°C, f=1.0 MHz)

SYMBOL	PARAMETER	TYPICAL	UNITS	TEST CONDITIONS
<b>C</b> <sub>1</sub>	Dedicated Input Capacitance	8	pf	V <sub>CC</sub> = 5.0V, V <sub>IN</sub> = 2.0V
<b>C</b> <sub>2</sub>	I/O Capacitance	9	pf	$V_{CC} = 5.0V, V_{I/O} = 2.0V$
<b>C</b> <sub>3</sub>	Clock Capacitance	15	pf	$V_{CC} = 5.0V, V_{Y} = 2.0V$

Table 2-0006/2064

# **Data Retention Specifications**

PARAMETER	MINIMUM	MAXIMUM	UNITS
Data Retention	20	_	Years
Erase/Reprogram Cycles	10000	-	Cycles

Table 2-0008/2064



## **Switching Test Conditions**

Input Pulse Levels	GND to 3.0V			
Input Rise and Fall Time	-125 ≤ 2 ns			
10% to 90%	Others	≤ 3 ns		
Input Timing Reference Levels	1.5V			
Output Timing Reference Levels 1.5V				
Output Load See Figure 2				

<sup>3-</sup>state levels are measured 0.5V from steady-state active level.

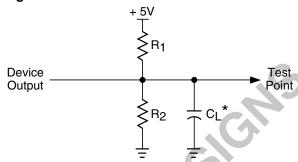
Table 2-0003/2064

#### **Output Load Conditions (see Figure 2)**

	TEST CONDITION	R1	R2	CL
Α		470Ω	390Ω	35pF
В	Active High	∞	390Ω	35pF
В	Active Low	470Ω	390Ω	35pF
С	Active High to Z at <b>V</b> <sub>OH</sub> -0.5V	-	390Ω	5pF
	Active Low to Z at <b>V</b> <sub>OL</sub> +0.5V	470Ω	390Ω	5pF

Table 2-0004/2064

#### Figure 2. Test Load



\*CL includes Test Fixture and Probe Capacitance.

### **DC Electrical Characteristics**

#### **Over Recommended Operating Conditions**

SYMBOL	PARAMETER	CONDITIO	MIN.	TYP.3	MAX.	UNITS	
<b>V</b> OL	Output Low Voltage	I <sub>OL</sub> = 8 mA		_	-	0.4	V
<b>V</b> OH	Output High Voltage	I <sub>OH</sub> = -4 mA		2.4	_	_	V
<b>I</b> IL	Input or I/O Low Leakage Current	$0V \le V_{IN} \le V_{IL}(Max.)$		_	_	-10	μΑ
<b>I</b> IH	Input or I/O High Leakage Current	$3.5V \le V_{IN} \le V_{CC}$		_	_	10	μΑ
IL-isp	ispEN Input Low Leakage Current	$0V \leq V_{IN} \leq V_{IL}$		_	_	-150	μΑ
<b>I</b> IL-PU	I/O Active Pull-Up Current	$0V \leq V_{IN} \leq V_{IL}$	_	_	-150	μΑ	
los1	Output Short Circuit Current	$V_{CC} = 5V, V_{OUT} = 0.5V$		_	_	-200	mA
ICC <sup>2, 4</sup>	Operating Power Supply Current	$V_{IL} = 0.0V, V_{IH} = 3.0V$	Commercial	_	95	175	mA
Operating Fower Supply Current		f <sub>CLOCK</sub> = 1 MHz	Industrial	_	95	_	mA

Table 2-0007/2064

- 1. One output at a time for a maximum duration of one second. V<sub>OUT</sub> = 0.5V was selected to avoid test problems by tester ground degradation. Characterized but not 100% tested.
- 2. Measured using four 16-bit counters.
- 3. Typical values are at  $V_{CC}$ = 5V and  $T_A$ = 25°C.
- 4. Maximum I<sub>CC</sub> varies widely with specific device configuration and operating frequency. Refer to the Power Consumption section of this data sheet and Thermal Management section of the Lattice Semiconductor Data Book or CD-ROM to estimate maximum I<sub>CC</sub>.

Table 2 - 0030B/2064-130



## **External Timing Parameters**

#### **Over Recommended Operating Conditions**

DADAMETED TEST <sup>4</sup> #		<b>#</b> <sup>2</sup>	propurtiou!		25	-100		-80		што
PARAMETER	COND. # DES		DESCRIPTION <sup>1</sup>	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	UNITS
<b>t</b> pd1	Α	1	Data Propagation Delay, 4PT Bypass, ORP Bypass	_	7.5	_	10.0	_	15.0	ns
<b>t</b> pd2	Α	2	Data Propagation Delay	_	10.0	_	13.0	_	18.5	ns
<b>f</b> max	Α	3	Clock Frequency with Internal Feedback <sup>3</sup>	125	_	100	_	81.0	1	MHz
<b>f</b> max (Ext.)	_	4	Clock Frequency with External Feedback $\left(\frac{1}{tsu2 + tco1}\right)$	100	_	77.0	_	57.0	-	MHz
<b>f</b> max (Tog.)	_	5	Clock Frequency, Max. Toggle	125	_	111	- (	100	_	MHz
<b>t</b> su1	_	6	GLB Reg. Setup Time before Clock, 4 PT Bypass 5.0 - 6.5 -		9.0	_	ns			
<b>t</b> co1	Α	7	GLB Reg. Clock to Output Delay, ORP Bypass - 4.0 -		->	5.0	_	6.5	ns	
<b>t</b> h1	_	8	GLB Reg. Hold Time after Clock, 4 PT Bypass		_	0.0	-	0.0	_	ns
<b>t</b> su2	_	9	GLB Reg. Setup Time before Clock		-	8.0	_	11.0	_	ns
<b>t</b> co2	_	10	GLB Reg. Clock to Output Delay		4.5	/_	6.0	_	8.0	ns
<b>t</b> h2	_	11	GLB Reg. Hold Time after Clock	0.0	7-	0.0	_	0.0	_	ns
<b>t</b> r1	Α	12	Ext. Reset Pin to Output Delay	7	10.0	_	13.5	_	17.0	ns
<b>t</b> rw1	_	13	Ext. Reset Pulse Duration	5.0	_	6.5	_	10.0	_	ns
<b>t</b> ptoeen	В	14	Product Term OE, Enable	-	12.0	_	15.0	_	18.0	ns
<b>t</b> ptoedis	С	15	Product Term OE, Disable	_	12.0	_	15.0	_	18.0	ns
<b>t</b> goeen	В	16	Global OE, Enable		7.0	_	9.0	_	12.0	ns
<b>t</b> goedis	С	17	Global OE, Disable – 7.0		_	9.0	_	12.0	ns	
<b>t</b> wh	_	18	External Synchronous Clock Pulse Duration, High	4.0	-	4.5	_	5.0	_	ns
twl	_	19	External Synchronous Clock Pulse Duration, Low	4.0	_	4.5	_	5.0	_	ns

- 1. Unless noted otherwise, all parameters use the GRP, 20 PTXOR path, ORP and Y0 clock.
- 2. Refer to Timing Model in this data sheet for further details.
- 3. Standard 16-bit counter using GRP feedback.
- 4. Reference Switching Test Conditions section.

JSE ISP



## Internal Timing Parameters<sup>1</sup>

## **Over Recommended Operating Conditions**

PARAMETER	TER # <sup>2</sup> DESCRIPTION -12				-1	00	-80		UNITS
TAHAMETER	π	DECOMIN HON	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	OMITO
Inputs									
<b>t</b> io	20	Input Buffer Delay	_	0.2	_	0.5	_	1.8	ns
<b>t</b> din	21	Dedicated Input Delay	_	1.5	_	2.2	- 4	4.4	ns
GRP									
<b>t</b> grp	22	GRP Delay	_	1.3	_	1.7		2.6	ns
GLB						C			
<b>t</b> 4ptbp	23	4 Product Term Bypass Comb. Path Delay	_	4.5	4	5.8	_	8.1	ns
<b>t</b> 4ptbp	24	4 Product Term Bypass Reg. Path Delay	_	5.0		5.8	_	6.8	ns
<b>t</b> 1ptxor	25	1 Product Term/XOR Path Delay	_	5.7	Y	6.8	_	8.0	ns
<b>t</b> 20ptxor	26	20 Product Term/XOR Path Delay	-	6.0	_	7.3	_	8.8	ns
<b>t</b> xoradj	27	XOR Adjacent Path Delay <sup>3</sup>	-	6.5	_	8.0	_	9.8	ns
<b>t</b> gbp	28	GLB Register Bypass Delay	Y	0.5	_	0.5	_	1.3	ns
<b>t</b> gsu	29	GLB Register Setup Time before Clock	0.8	_	1.2	_	1.4	_	ns
<b>t</b> gh	30	GLB Register Hold Time after Clock	3.0	_	4.0	_	6.0	_	ns
<b>t</b> gco	31	GLB Register Clock to Output Delay	_	0.2	_	0.3	_	0.4	ns
<b>t</b> gro	32	GLB Register Reset to Output Delay	_	1.1	_	1.3	_	1.6	ns
<b>t</b> ptre	33	GLB Product Term Reset to Register Delay	_	4.8	_	6.1	_	8.6	ns
<b>t</b> ptoe	34	GLB Product Term Output Enable to I/O Cell Delay	_	7.3	_	8.6	_	9.0	ns
<b>t</b> ptck	35	GLB Product Term Clock Delay	3.3	5.6	4.1	7.1	5.6	10.2	ns
ORP									
<b>t</b> orp	36	ORP Delay	_	0.8	-	1.4	-	2.0	ns
<b>t</b> orpbp	37	ORP Bypass Delay	_	0.3	ı	0.4	_	0.5	ns
Outputs									
<b>t</b> ob	38	Output Buffer Delay	_	1.2	_	1.6	_	2.0	ns
tsl	39	Output Slew Limited Delay Adder	_	10.0	_	10.0	-	10.0	ns
<b>t</b> oen	40	I/O Cell OE to Output Enabled	_	3.2	_	4.2	-	4.6	ns
todis	41	I/O Cell OE to Output Disabled	_	3.2	-	4.2	_	4.6	ns
<b>t</b> goe	42	Global Output Enable	_	3.8	-	4.8		7.4	ns
Clocks									
<b>t</b> gy0	43	Clock Delay, Y0 to Global GLB Clock Line (Ref. clock)	2.3	2.3	2.7	2.7	3.6	3.6	ns
<b>t</b> gy1/2	44	Clock Delay, Y1 or Y2 to Global GLB Clock Line 2.3 2.3 2.7 2.7 3.6 3.0						3.6	ns
Global Re	set								
<b>t</b> gr	45	Global Reset to GLB	_	6.9	_	9.2	_	11.4	ns

<sup>1.</sup> Internal Timing Parameters are not tested and are for reference only.

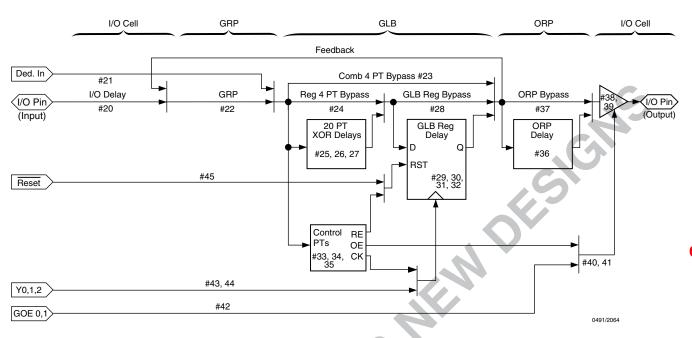
Table 2- 0036C/2064-130

<sup>2.</sup> Refer to Timing Model in this data sheet for further details.

<sup>3.</sup> The XOR adjacent path can only be used by hard macros.



## ispLSI 2064/A Timing Model



#### Derivations of tsu, th and tco from the Product Term Clock<sup>1</sup>

```
\begin{array}{lll} \textbf{tsu} &=& \text{Logic} + \text{Reg su} - \text{Clock (min)} \\ &=& (\textbf{tio} + \textbf{tgrp} + \textbf{t}20\text{ptxor}) + (\textbf{tgsu}) - (\textbf{tio} + \textbf{tgrp} + \textbf{tptck(min)}) \\ &=& (\#20 + \#22 + \#26) + (\#29) - (\#20 + \#22 + \#35) \\ 3.5 \text{ ns} &=& (0.2 + 1.3 + 6.0) + (0.8) - (0.2 + 1.3 + 3.3) \\ \\ \textbf{th} &=& \text{Clock (max)} + \text{Reg h} - \text{Logic} \\ &=& (\textbf{tio} + \textbf{tgrp} + \textbf{tptck(max)}) + (\textbf{tgh}) - (\textbf{tio} + \textbf{tgrp} + \textbf{t}20\text{ptxor}) \\ &=& (\#20 + \#22 + \#35) + (\#30) - (\#20 + \#22 + \#26) \\ 2.6 \text{ ns} &=& (0.2 + 1.3 + 5.6) + (3.0) - (0.2 + 1.3 + 6.0) \\ \\ \textbf{tco} &=& \text{Clock (max)} + \text{Reg co} + \text{Output} \\ &=& (\textbf{tio} + \textbf{tgrp} + \textbf{tptck(max)}) + (\textbf{tgco}) + (\textbf{torp} + \textbf{tob}) \\ &=& (\#20 + \#22 + \#35) + (\#31) + (\#36 + \#38) \\ 9.4 \text{ ns} &=& (0.2 + 1.3 + 5.6) + (0.2) + (0.8 + 1.2) \\ \end{array}
```

Table 2- 0042A-2064

Note: Calculations are based upon timing specifications for the ispLSI 2064/A-125L.

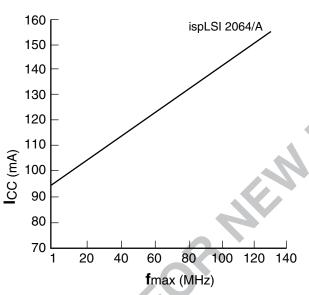


#### **Power Consumption**

Power consumption in the ispLSI 2064 and 2064A devices depends on two primary factors: the speed at which the device is operating and the number of Product Terms

used. Figure 4 shows the relationship between power and operating speed.

Figure 4. Typical Device Power Consumption vs fmax



Notes: Configuration of Four 16-bit Counters Typical Current at 5V, 25° C

ICC can be estimated for the ispLSI 2064/A using the following equation:

 $I_{CC}(mA) = 38 + (\# \text{ of PTs} * 0.33) + (\# \text{ of nets} * Max freq * 0.007)$ 

Where:

# of PTs = Number of Product Terms used in design

# of nets = Number of Signals used in device

Max freq = Highest Clock Frequency to the device (in MHz)

The ICC estimate is based on typical conditions ( $V_{CC} = 5.0V$ , room temperature) and an assumption of two GLB loads on average exists. These values are for estimates only. Since the value of I<sub>CC</sub> is sensitive to operating conditions and the program in the device, the actual I<sub>CC</sub> should be verified.

0127A/2064A



# Pin Description

NAME	PLCC PIN NUMBERS	DESCRIPTION
I/O 0 - I/O 3 I/O 4 - I/O 7 I/O 8 - I/O 11 I/O 12 - I/O 15 I/O 16 - I/O 19 I/O 20 - I/O 23 I/O 24 - I/O 27 I/O 28 - I/O 31 I/O 32 - I/O 35 I/O 36 - I/O 39 I/O 40 - I/O 43 I/O 44 - I/O 47 I/O 48 - I/O 51 I/O 52 - I/O 55 I/O 56 - I/O 59 I/O 60 - I/O 63	26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58, 59, 60, 68, 69, 70, 71, 72, 73, 74, 75, 76, 77, 78, 79, 80, 81, 82, 83, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18	Input/Output Pins — These are the general purpose I/O pins used by the logic array.
GOE 0, GOE 1	67, 84	Global Output Enable input pins.
Y0, Y1, Y2 RESET	20, 66, 63	Dedicated Clock input. This clock input is connected to one of the clock inputs of all the GLBs in the device.  Active Low (0) Reset pin which resets all registers in the device.
NESET	24	Active Low (0) neset pirt which resets all registers in the device.
ispEN	23	Input — Dedicated in-system programming enable pin. This pin is brought low to enable the programming mode. When low, the MODE, SDI, SDO and SCLK controls become active.
SDI/ IN 0 <sup>2</sup>	25	Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as an input pin to load programming data into the device. SDI/IN 0 also is used as one of the two control pins for the ISP state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated pin input.
MODE/ IN 1 <sup>2</sup>	42	Input — This pin performs two functions. When ispEN is logic low, it functions as a pin to control the operation of the ISP state machine. When ispEN is high, it functions as a dedicated input pin.
SDO/IN 2 <sup>2</sup>	44	Output/Input — This pin performs two functions. When ispEN is logic low, it functions as an output pin to read serial shift register data. When ispEN is high, it functions as a dedicated input pin.
SCLK/IN 3 <sup>2</sup>	61	Input — This pin performs two functions. When ispEN is logic low, it functions as a clock pin for the Serial Shift Register. When ispEN is high, it functions as a dedicated input pin.
GND	1, 22, 43, 64	Ground (GND)
vcc	21, 65	Vcc
NC <sup>1</sup>	2, 19, 62	No Connect

<sup>1.</sup> NC pins are not to be connected to any active signals, VCC or GND.

2. Pins have dual function capability.

Table 2-0002A-08isp/2064



# Pin Description

NAME	TQF	P PIN	NUME	BERS	DESCRIPTION
I/O 0 - I/O 3 I/O 4 - I/O 7 I/O 8 - I/O 11 I/O 12 - I/O 15 I/O 16 - I/O 19 I/O 20 - I/O 23 I/O 24 - I/O 27 I/O 28 - I/O 31 I/O 32 - I/O 35 I/O 36 - I/O 39 I/O 40 - I/O 43 I/O 44 - I/O 47 I/O 48 - I/O 51 I/O 52 - I/O 55 I/O 56 - I/O 59	17, 21, 29, 33, 40, 44, 48, 56, 67, 71, 79, 83, 90, 94,	18, 22, 30, 34, 41, 45, 53, 57, 68, 72, 80, 84, 91, 95, 3,	19, 23, 31, 35, 42, 46, 54, 58, 69, 73, 81, 85, 92, 96, 4,	20, 28, 32, 36, 43, 47, 55, 59, 70, 78, 82, 86, 93, 97, 5,	Input/Output Pins - These are the general purpose I/O pins used by the logic array.
I/O 60 - I/O 63 GOE 0, GOE 1	6, 66,	7, 87	8,	9	Global Output Enable input pins.
Y0, Y1, Y2	11,	65,	62		Dedicated Clock input. This clock input is connected to one of the clock inputs of all of the GLBs on the device.
RESET	15				Active Low (0) Reset pin which resets all of the registers in the device.
ispEN SDI/IN 0 <sup>2</sup>	14 16				Input – Dedicated in-system programming enable input pin. This pin is brought low to enable the programming mode. The MODE, SDI, SDO and SCLK controls become active.  Input – This pin performs two functions. When ispEN is logic low, it functions as an input pin to load programming data into the device. SDI/IN 0 also is used as one of the two control pins for the ISP state machine. When ispEN is high, it functions as a dedicated input pin.
MODE/IN 1 <sup>2</sup>	37			SA	Input – This pin performs two functions. When ispEN is logic low, it functions as a pin to control the operation of the ISP state machine.
SDO/IN 2 <sup>2</sup>	39		2	2	When ispEN is high, it functions as a dedicated input pin.  Output/Input – This pin performs two functions. When ispEN is logic low, it functions as an output pin to read serial shift register data. When ispEN is high, it functions as a dedicated input pin.
SCLK/IN 3 <sup>2</sup>	60	5			Input – This pin performs two functions. When ispEN is logic low, it functions as a clock pin for the Serial Shift Register. When ispEN is high, it functions as a dedicated input pin.
GND	13,	38,	63,	88	Ground (GND)
VCC	12,	64			V <sub>CC</sub>
NC <sup>1</sup>	1, 25, 50, 74, 89,	2, 26, 51, 75, 99,	10, 27, 52, 76, 100	24, 49, 61, 77,	No Connect.

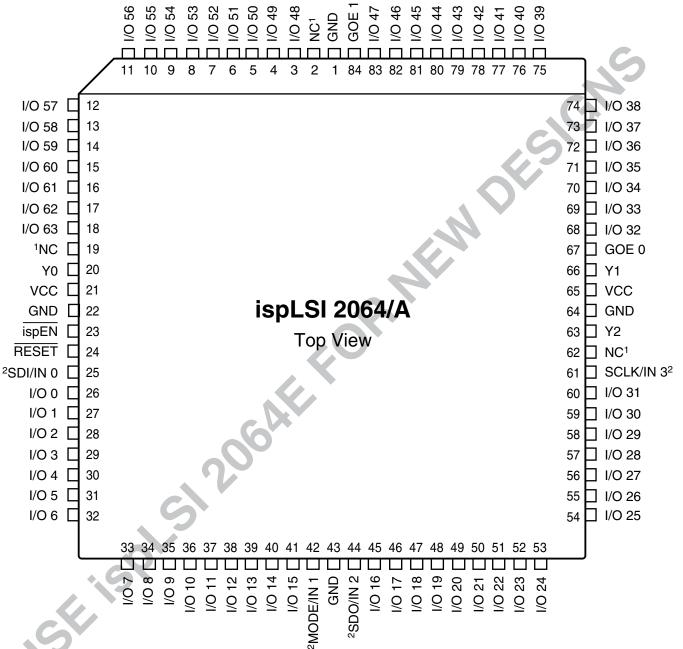
1. NC pins are not to be connected to any active signals, VCC or GND.

2. Pins have dual function capability.

Table 2-0002-2064b.eps

# Pin Configuration

#### ispLSI 2064/A 84-Pin PLCC Pinout Diagram



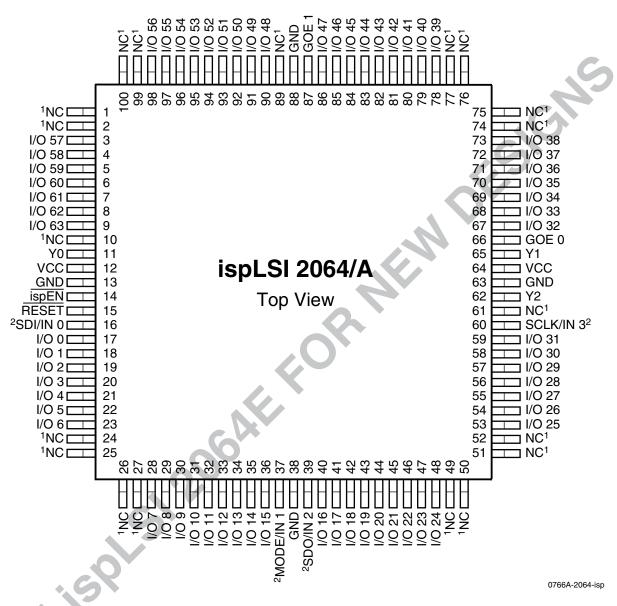
- 1. NC pins are not to be connected to any active signals, VCC or GND.
- 2. Pins have dual function capability.

0123A/2064



## **Pin Configuration**

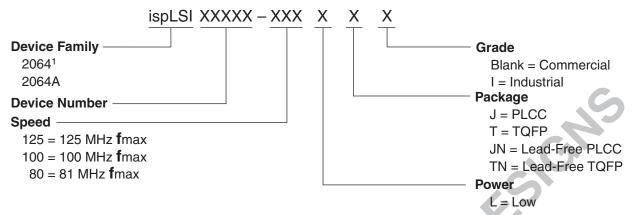
#### ispLSI 2064/A 100-Pin TQFP Pinout Diagram



- 1. NC pins are not to be connected to any active signals, VCC or GND.
- 2. Pins have dual function capability.



## **Part Number Description**



1. Discontinued per PCN #02-06. Contact Rochester Electronics for available inventory.

# ispLSI 2064/A Ordering Information

## **Conventional Packaging**

### COMMERCIAL

FAMILY	fmax (MHz)	tpd (ns)	ORDERING NUMBER	PACKAGE
	125	7.5	ispLSI 2064A-125LJ84	84-Pin PLCC
	125	7.5	ispLSI 2064A-125LT100	100-Pin TQFP
	100	10	ispLSI 2064A-100LJ84	84-Pin PLCC
	100	10	ispLSI 2064A-100LT100	100-Pin TQFP
	81	15	ispLSI 2064A-80LJ84	84-Pin PLCC
ispLSI	81	15	ispLSI 2064A-80LT100	100-Pin TQFP
	125	7.5	ispLSI 2064-125LJ <sup>1</sup>	84-Pin PLCC
	125	7.5	ispLSI 2064-125LT <sup>1</sup>	100-Pin TQFP
	100	10	ispLSI 2064-100LJ <sup>1</sup>	84-Pin PLCC
	100	10	ispLSI 2064-100LT <sup>1</sup>	100-Pin TQFP
	81	15	ispLSI 2064-80LJ <sup>1</sup>	84-Pin PLCC
	81	15	ispLSI 2064-80LT <sup>1</sup>	100-Pin TQFP

<sup>1.</sup> Discontinued per PCN #02-06. Contact Rochester Electronics for available inventory.

#### **INDUSTRIAL**

FAMILY	fmax (MHz)	tpd (ns)	ORDERING NUMBER	PACKAGE
ispLSI	81	15	ispLSI 2064A-80LJ84I	84-Pin PLCC
	81	15	ispLSI 2064A-80LT100I	100-Pin TQFP
	81	15	ispLSI 2064-80LJI <sup>1</sup>	84-Pin PLCC
	81	15	ispLSI 2064-80LTI <sup>1</sup>	100-Pin TQFP

<sup>1.</sup> Discontinued per PCN #02-06. Contact Rochester Electronics for available inventory.



## ispLSI 2064/A Ordering Information (Cont.)

## **Lead-Free Packaging**

#### **COMMERCIAL**

FAMILY	fmax (MHz)	tpd (ns)	ORDERING NUMBER	PACKAGE
ispLSI	125	7.5	ispLSI 2064A-125LJN84 <sup>1</sup>	Lead-Free 84-Pin PLCC
	125	7.5	ispLSI 2064A-125LTN100	Lead-Free 100-Pin TQFP
	100	10	ispLSI 2064A-100LJN84 <sup>1</sup>	Lead-Free 84-Pin PLCC
	100	10	ispLSI 2064A-100LTN100	Lead-Free 100-Pin TQFP
	81	15	ispLSI 2064A-80LJN841	Lead-Free 84-Pin PLCC
	81	15	ispLSI 2064A-80LTN100	Lead-Free 100-Pin TQFP

<sup>1. 84-</sup>PLCC lead-free package is MSL4. Refer to "Handling Moisture Sensitive Packages" document on www.latticesemi.com.

#### **INDUSTRIAL**

FAMILY	fmax (MHz)	tpd (ns)	ORDERING NUMBER	PACKAGE
ispLSI	81	15	ispLSI 2064A-80LJN84I¹	Lead-Free 84-Pin PLCC
	81	15	ispLSI 2064A-80LTN100I	Lead-Free 100-Pin TQFP

<sup>1. 84-</sup>PLCC lead-free package is MSL4. Refer to "Handling Moisture Sensitive Packages" document on www.latticesemi.com.

# **Revision History**

Date	Version	Change Summary
_	09	Previous Lattice release.
August 2006	10	Updated for lead-free package options.